

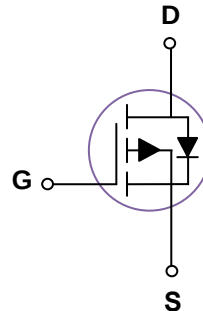
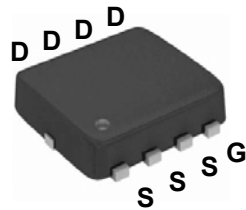
General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

V_{DS}	-30V
I_D (at $V_{GS}=-10V$)	-30A
$R_{DS(ON)}$ (at $V_{GS}=-10V$)	15m Ω (Typ)
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$)	19m Ω (Typ)

PDFN3*3



Absolute Maximum Ratings $T_A=25^{\circ}C$ unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V _{DS}	-30	V
Gate-Source Voltage		V _{GS}	±20	V
Drain Current-Continuous	TC=25°C	I _D	-30	A
	TC=100°C	I _D	-19	A
Drain Current – Pulsed		I _{DM}	-120	A
Maximum Power Dissipation		P _D	23	W
Junction and Storage Temperature Range		T _J ,T _{STG}	-55 To 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance junction-case	$R_{\theta JC}$		1.1	$^{\circ}C/W$
Thermal Resistance junction-to-Ambient	$R_{\theta JA}$		60	$^{\circ}C/W$

Electrical Characteristics (TJ=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =-250μA	-30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30V,V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V,V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} ,I _D =-250μA	-1.0	-1.5	-2.5	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-10V, I _D =-8.0A		15	20	mΩ
		V _{GS} =-4.5V, I _D =-5.0A		19	25	mΩ
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{DS} =-15V,V _{GS} =0V, F=1.0MHz		1630		pF
C _{oss}	Output Capacitance			180		pF
C _{rss}	Reverse Transfer Capacitance			125		pF
SWITCHING PARAMETERS						
t _{d(on)}	Turn-on Delay Time	V _{DS} =-15V,I _D =-1A, V _{GS} =-10V, R _G =6Ω		9		nS
t _r	Turn-on Rise Time			21		nS
t _{d(off)}	Turn-Off Delay Time			59		nS
t _f	Turn-Off Fall Time			14		nS
Q _g	Total Gate Charge	V _{DS} =-15V,I _D =-8A, V _{GS} =-4.5V		14		nC
Q _{gs}	Gate-Source Charge			4.1		nC
Q _{gd}	Gate-Drain Charge			6.3		nC
V _{SD}	Diode Forward Voltage	V _{GS} =0V,I _{SD} =-1A		0.72	1.4	V

Note:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

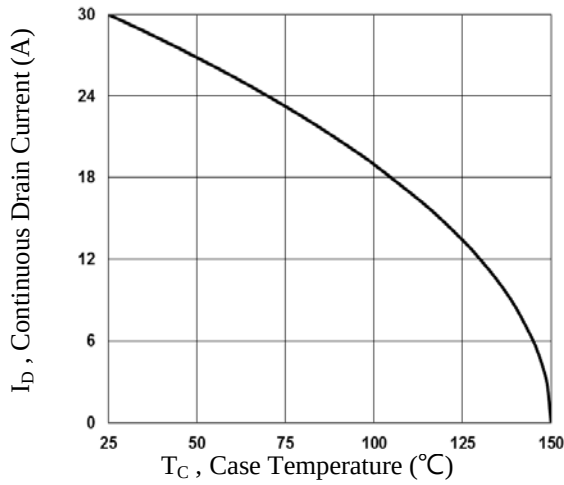


Fig.1 Continuous Drain Current vs. T_C

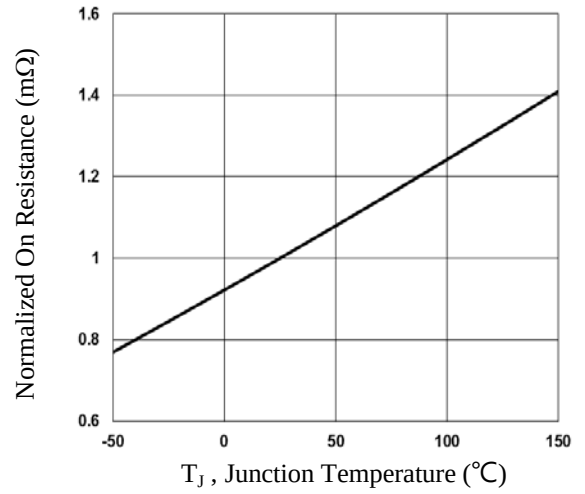


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

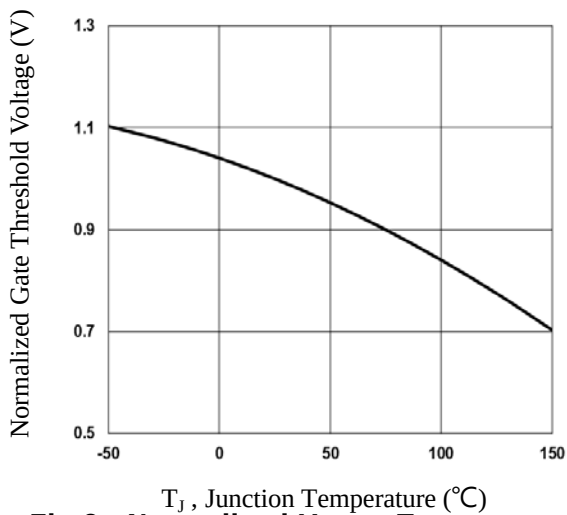


Fig.3 Normalized V_{th} vs. T_J

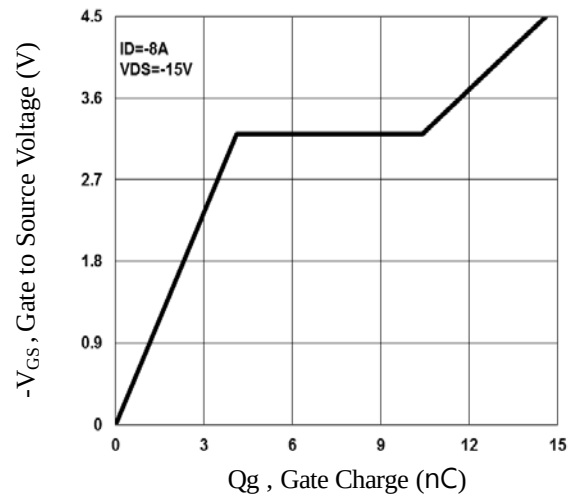


Fig.4 Gate Charge Waveform

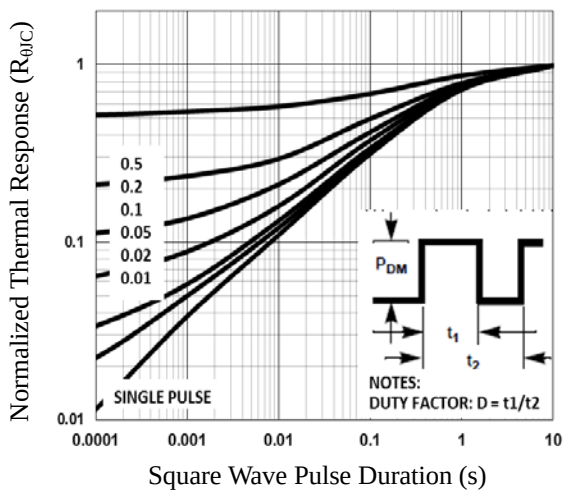


Fig.5 Normalized Transient Impedance

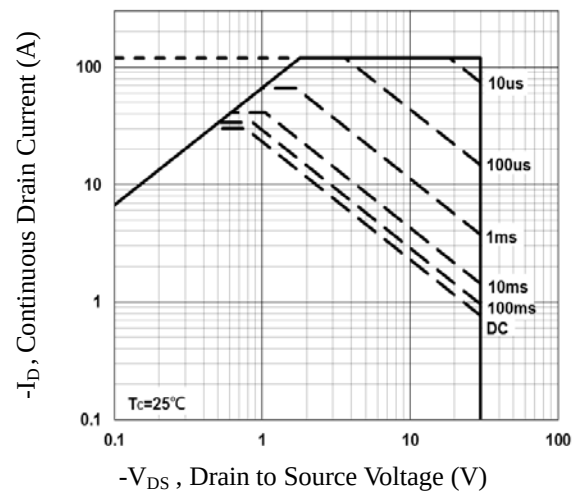


Fig.6 Maximum Safe Operation Area

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

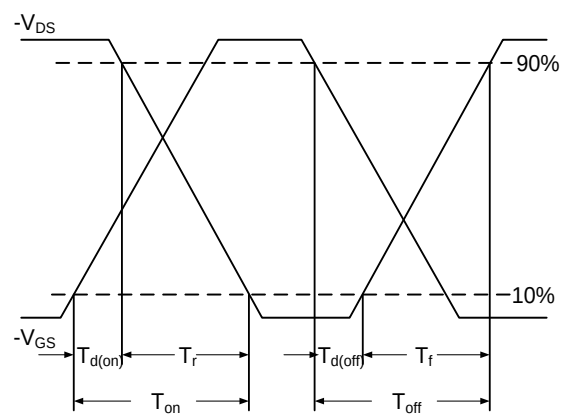


Fig.7 Switching Time Waveform

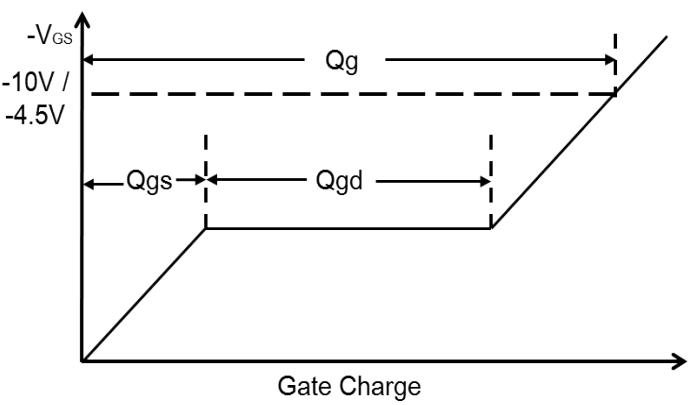
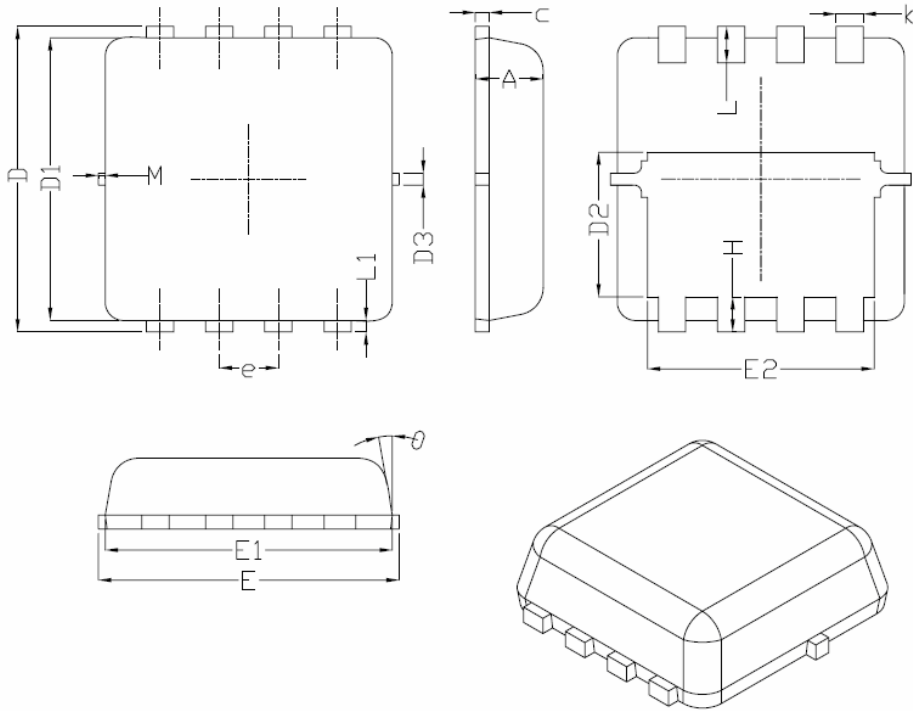


Fig.8 Gate Charge Waveform

PDFN3*3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.48	1.58	1.68
D3	-	0.13	-
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BS		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	-	0.13	-
M	*	*	0.15
θ		10°	12°